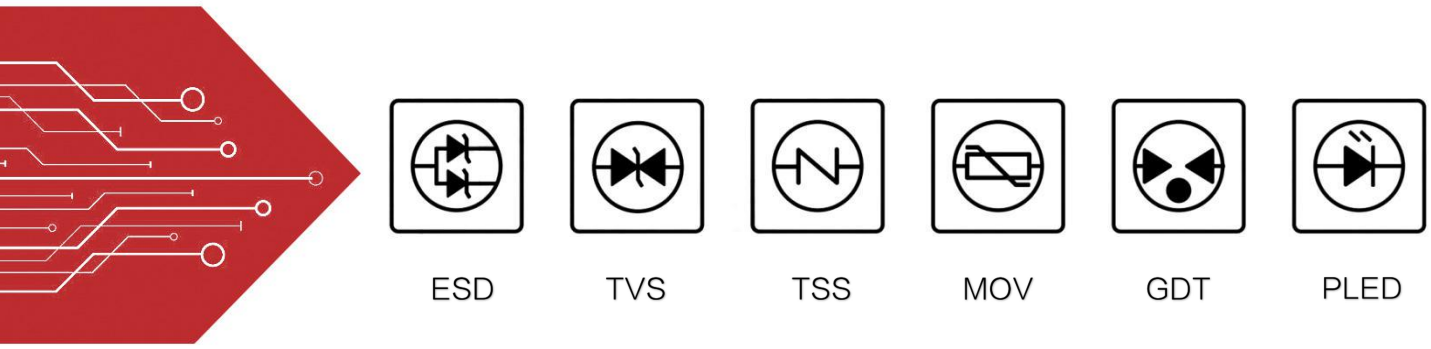
MSKSEMI
SEMICONDUCTOR



Product data sheet

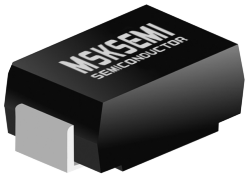
www.msksemi.com

VOLTAGE RANGE

20 to 100 Volts

CURRENT

5.0 Ampere



SMC

FEATURES

* Ideal for surface mount applications
* Easy pick and place
* Built-in strain relief
* Low forward voltage drop

MECHANICAL DATA

* Case: Molded plastic
* Epoxy: UL 94V-0 rate flame retardant
* Metallurgically bonded construction
* Polarity: Color band denotes cathode end
* Mounting position: Any
* Weight: 0.21 grams

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating 25℃ ambient temperature unless otherwise specified.
Single phase half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

P/N(MARK)	SK52C	SK53C	SK54C	SK55C	SK56C	SK58C	SK59C	SK510C	UNITS
Maximum Recurrent Peak Reverse Voltage	20	30	40	50	60	80	90	100	V
Maximum RMS Voltage	14	21	28	35	42	56	63	70	V
Maximum DC Blocking Voltage	20	30	40	50	60	80	90	100	V
Maximum Average Forward Rectified Current at T_L=90℃	5.0								A
Peak Forward Surge Current, 8.3 ms single half sine-wave superimposed on rated load (JEDEC method)	150								A
Maximum Instantaneous Forward Voltage at 5.0A	0.55			0.70		0.85			V
Maximum DC Reverse Current Ta=25℃	0.1					0.02			mA
at Rated DC Blocking Voltage Ta=100℃	5					2			mA
Typical Junction Capacitance (Note1)	300								pF
Typical Thermal Resistance R JL (Note 2)	10								℃/W
Operating Temperature Range T_J	-65 — +150								℃
Storage Temperature Range T_{STG}	-65 — +150								℃

NOTES:

1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.

2. Thermal Resistance Junction to Lead.

RATING AND CHARACTERISTIC CURVES (SK52C THRU SK510C)

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

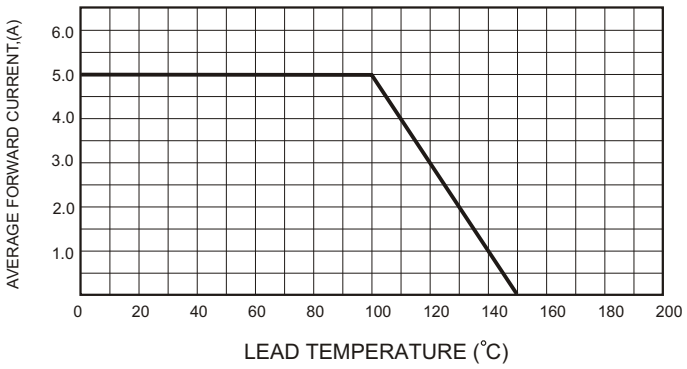


FIG.2-TYPICAL FORWARD CHARACTERISTICS

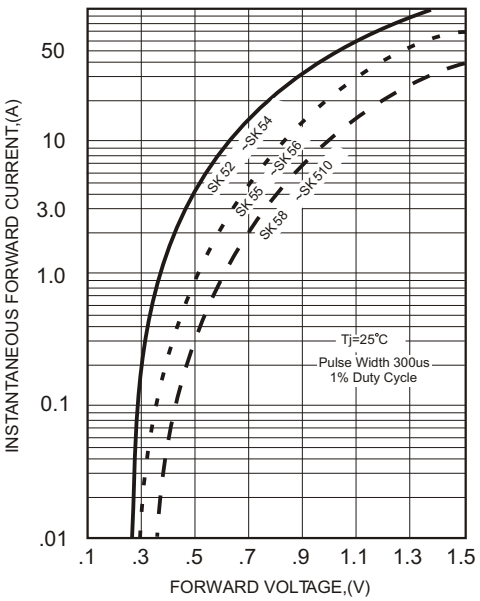


FIG.3-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

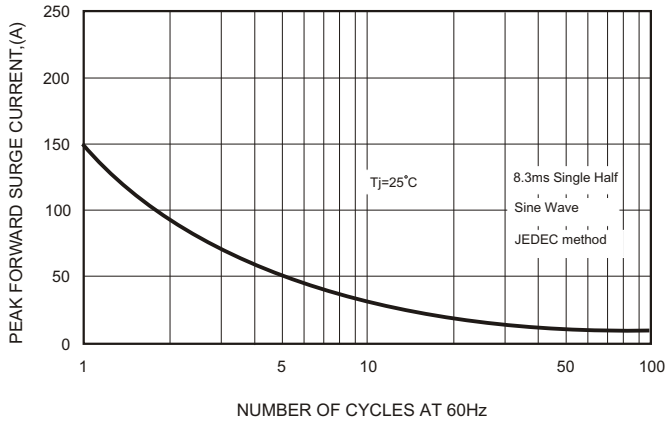


FIG.4-TYPICAL JUNCTION CAPACITANCE

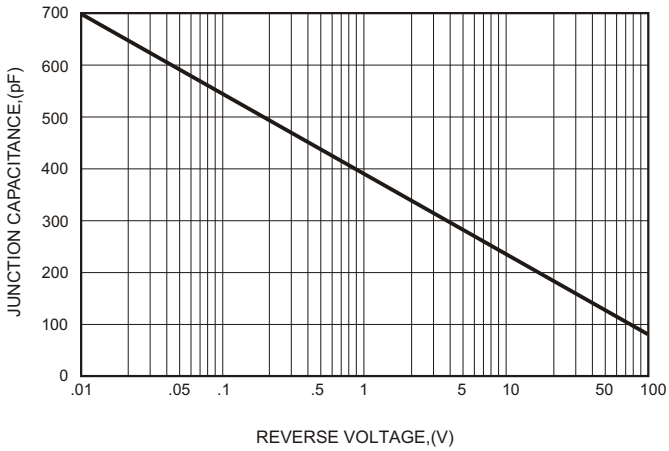
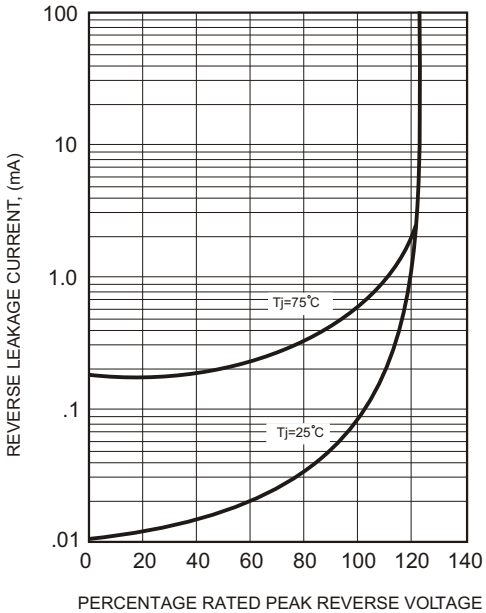
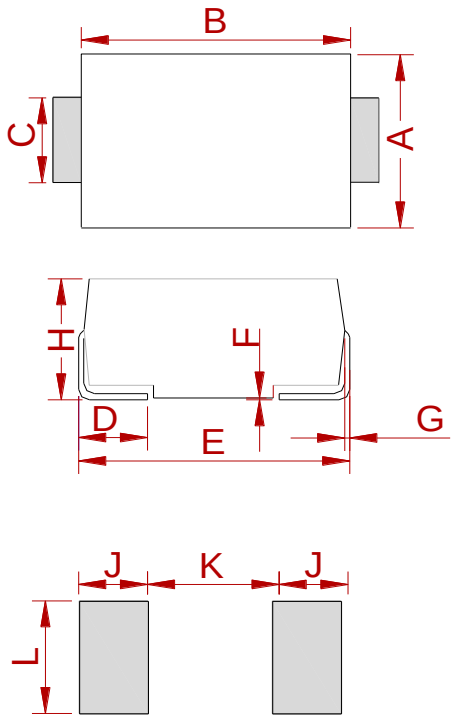


FIG.5 - TYPICAL REVERSE CHARACTERISTICS



PACKAGE MECHANICAL DATA



SMC

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	5.75	6.25	0.226	0.246
B	6.90	7.40	0.272	0.291
C	2.75	3.25	0.108	0.128
D	0.95	1.52	0.037	0.060
E	7.70	8.20	0.303	0.323
F	0.051	0.203	0.002	0.008
G	0.15	0.31	0.006	0.012
H	2.15	2.62	0.085	0.103
J	2.40		0.094	
K		4.20		0.165
L	3.30		0.130	

REEL SPECIFICATION

P/N	PKG	QTY
SK52C THRU SK510C	SMC	3000

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